



Material Composition Declaration

EPC2035

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	1.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	1.1602	87.82	90.41	878235
	Silicon oxide	7631-86-9	0.0050	0.38		3799
	Silicon nitride	12033-89-5	0.0017	0.13		1270
	Gallium nitride	25617-97-4	0.0060	0.45		4538
	Aluminum	7429-90-5	0.0095	0.72		7197
	Aluminum nitride	24304-00-5	0.0014	0.11		1094
	Titanium	7440-32-6	0.0002	0.02		179
	Titanium nitride	25583-20-4	0.0009	0.07		665
	Copper	7440-50-8	0.0003	0.02		239
	Tungsten	7440-33-7	0.0004	0.03		310
	Polyimide		0.0087	0.66		6576
Under Bump Metal	Titanium	7440-32-6	0.0001	0.01	0.16	60
	Nickel	7440-02-0	0.0000	0.00		0
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0020	0.15		1522
Solder Bar	Tin	7440-31-5	0.1190	9.01	9.43	90071
	Silver	7440-22-4	0.0050	0.38		3773
	Copper	7440-50-8	0.0006	0.05		472
Sum in total:			1.3	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.